

## 4.2 Board Layouts

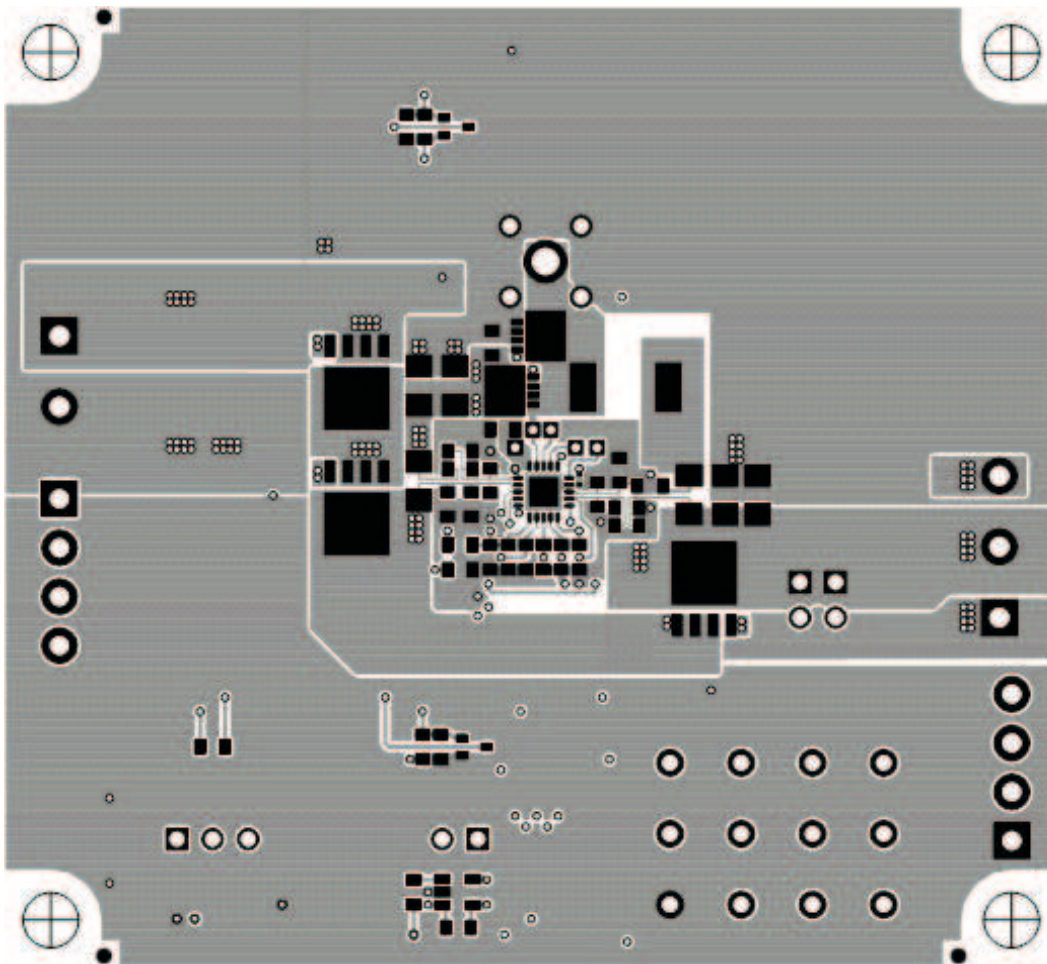


Figure 5. Top Layer

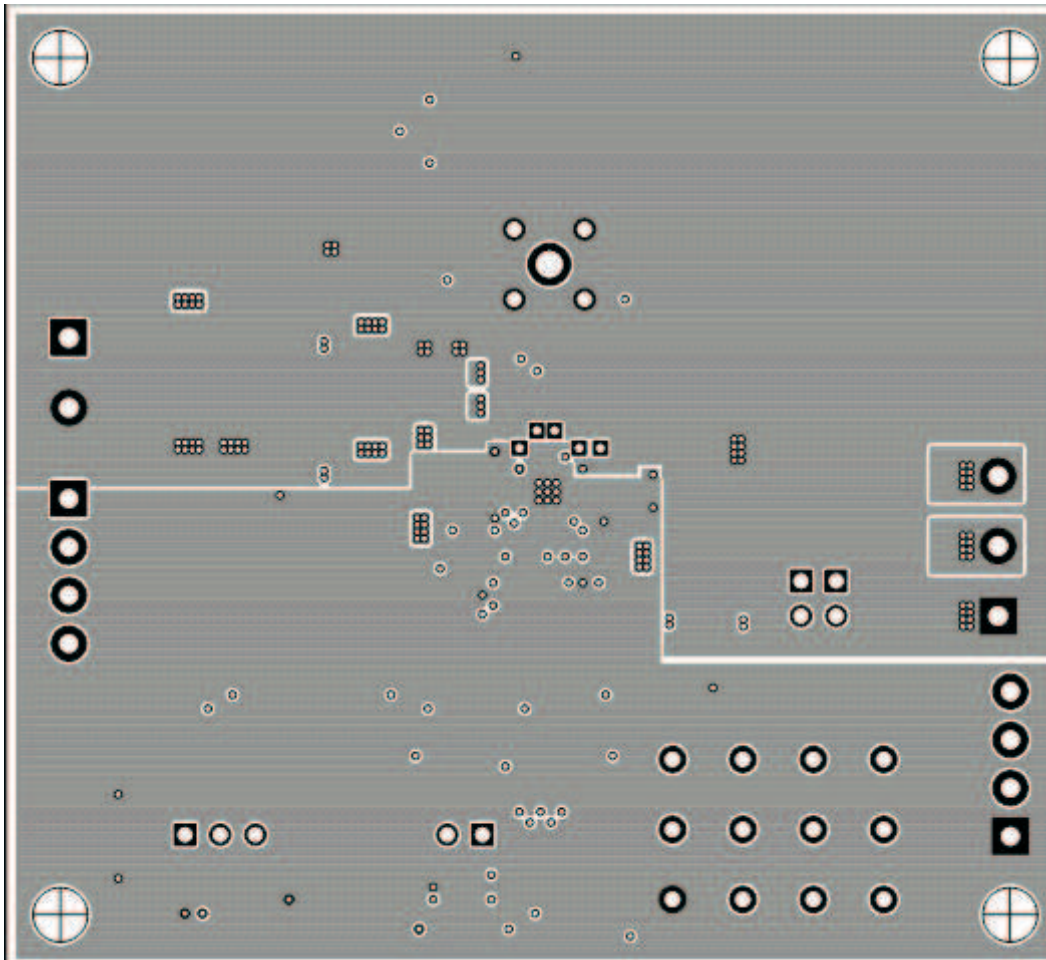
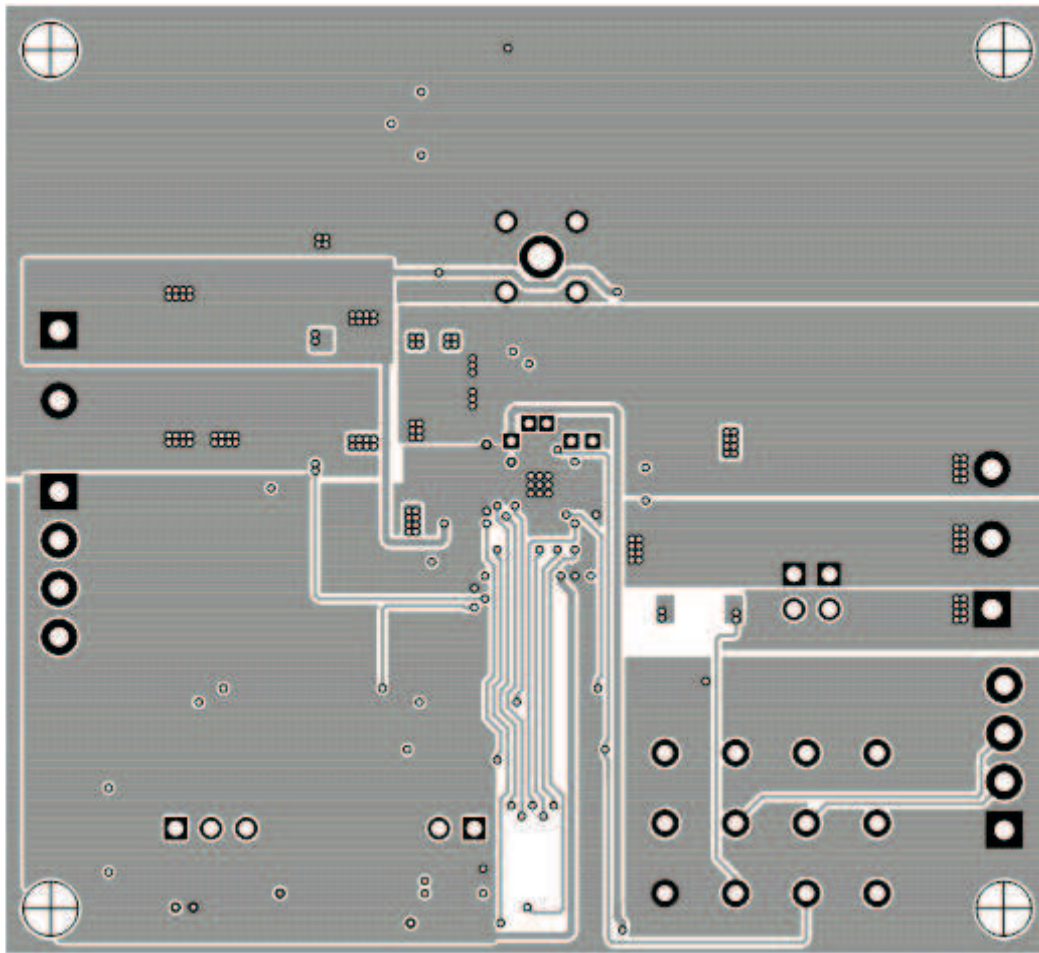


Figure 6. Second Layer



**Figure 7. Third Layer**

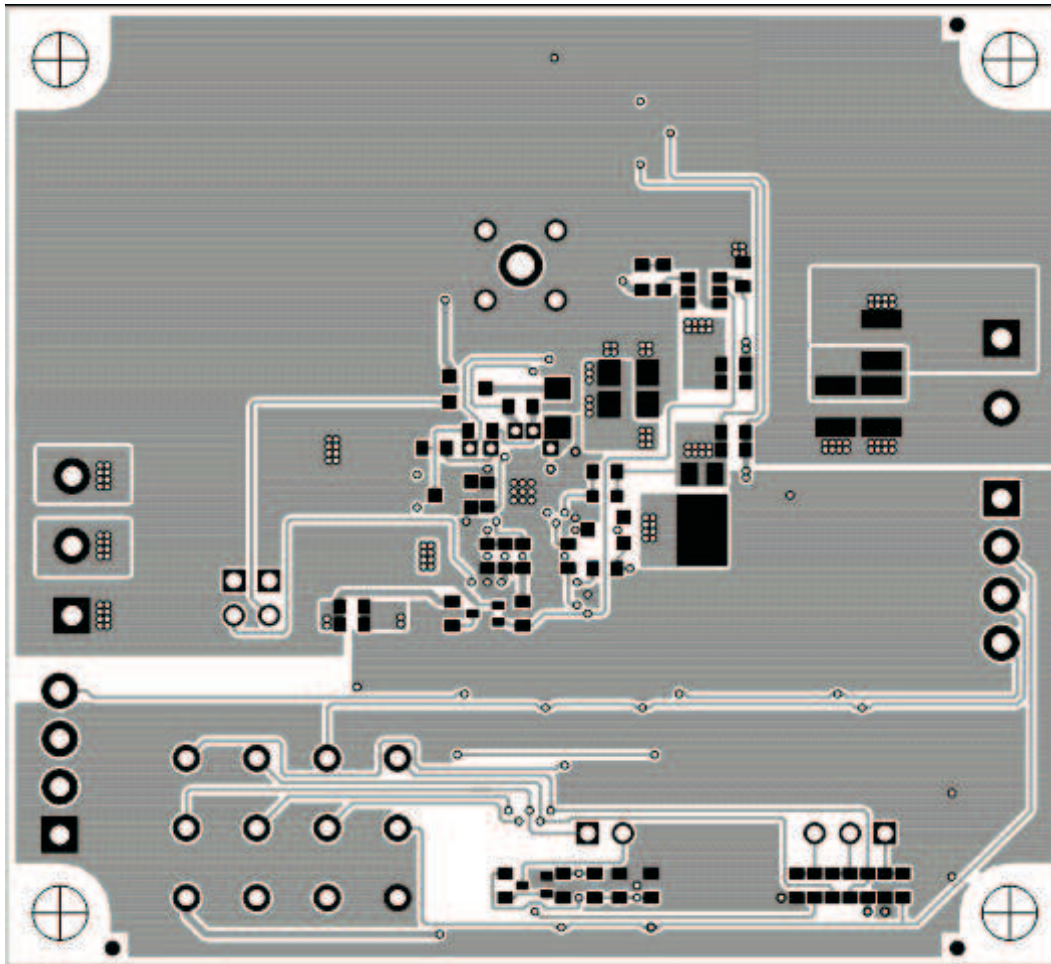


Figure 8. Bottom Layer

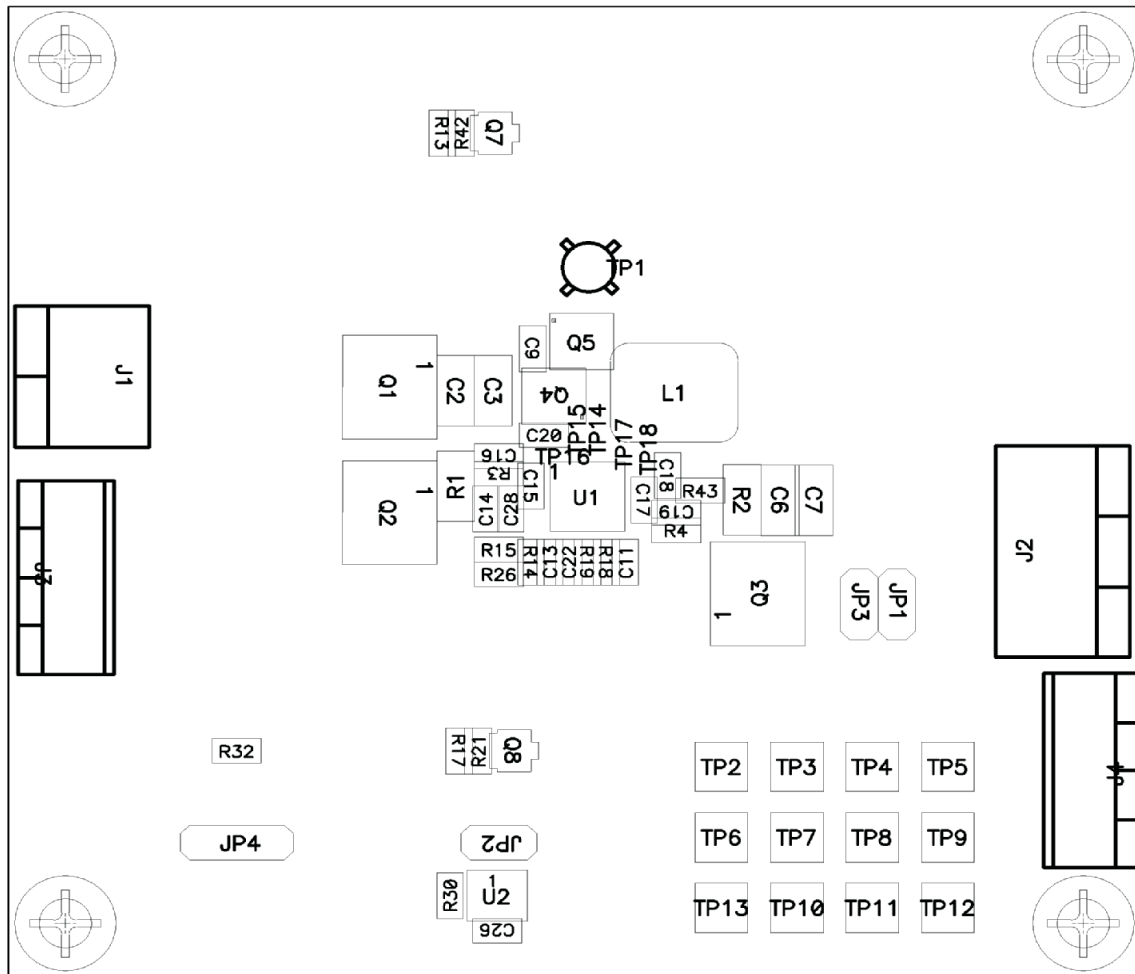
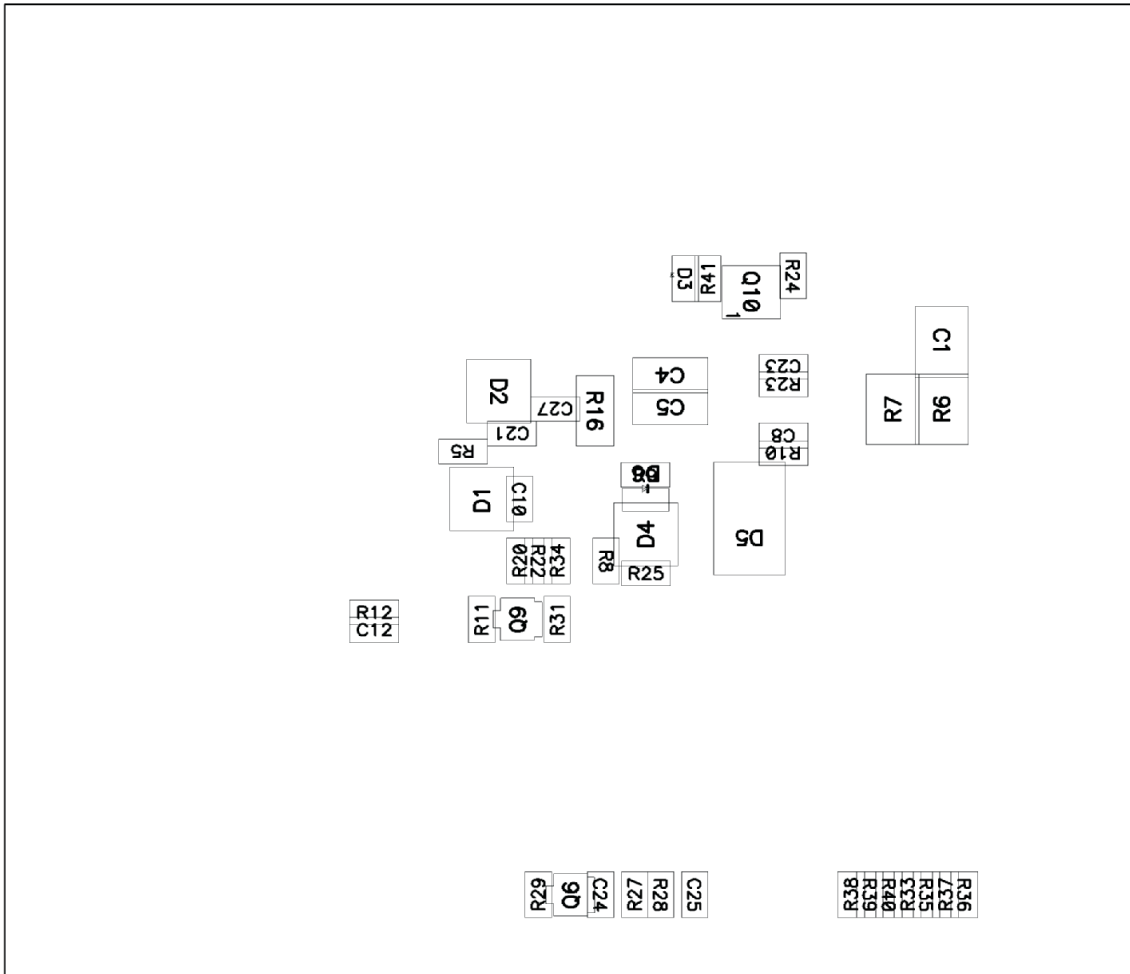


Figure 9. Top Assembly



**Figure 10. Bottom Assembly**

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